

Lecture 7

PN Junction and MOS Electrostatics(IV) Metal-Oxide-Semiconductor Structure

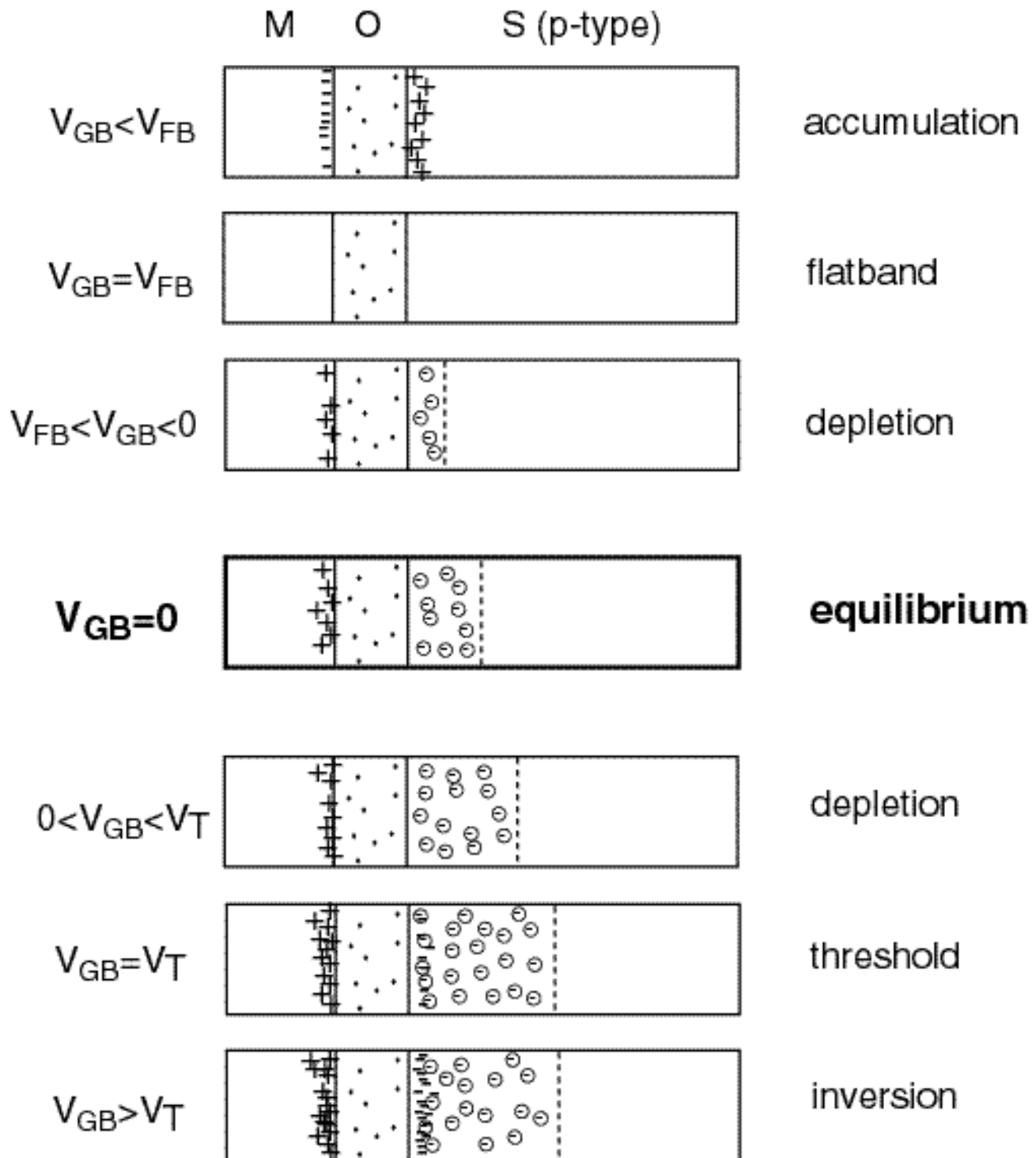
Outline

1. Overview of MOS electrostatics under bias
2. Depletion regime
3. Flatband
4. Accumulation regime
5. Threshold
6. Inversion regime

Reading Assignment:

Howe and Sodini, Chapter 3, Sections 3.8-3.9

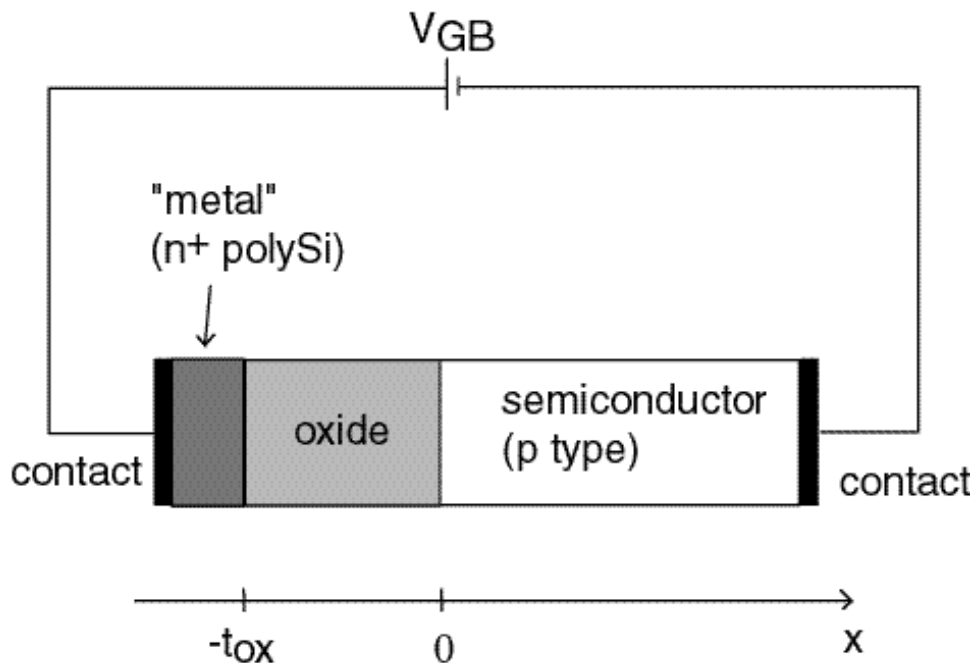
Summary of Key Concepts



In inversion:

$$|Q_n| = C_{ox} (V_{GB} - V_T) \quad \text{for } V_{GB} > V_T$$

1. Overview of MOS electrostatics under bias



Application of bias:

- Built-in potential across MOS structure increases from ϕ_B to $\phi_B + V_{GB}$
- Oxide forbids current flow \Rightarrow
 - $J=0$ everywhere in semiconductor
 - Need **drift = - diffusion** in SCR
- Must maintain boundary condition at Si/SiO₂ interface
 - $E_{ox} / E_s \approx 3$

How can this be accommodated simultaneously? \Rightarrow **quasi-equilibrium situation** with potential build-up across MOS equal to $\phi_B + V_{GB}$

Important consequence of quasi-equilibrium:

⇒ Boltzmann relations apply in semiconductor

[they were derived starting from $J_e = J_h = 0$]

$$\mathbf{n}(\mathbf{x}) = \mathbf{n}_i \mathbf{e}^{q\phi(\mathbf{x})/kT}$$

$$\mathbf{p}(\mathbf{x}) = \mathbf{n}_i \mathbf{e}^{-q\phi(\mathbf{x})/kT}$$

and

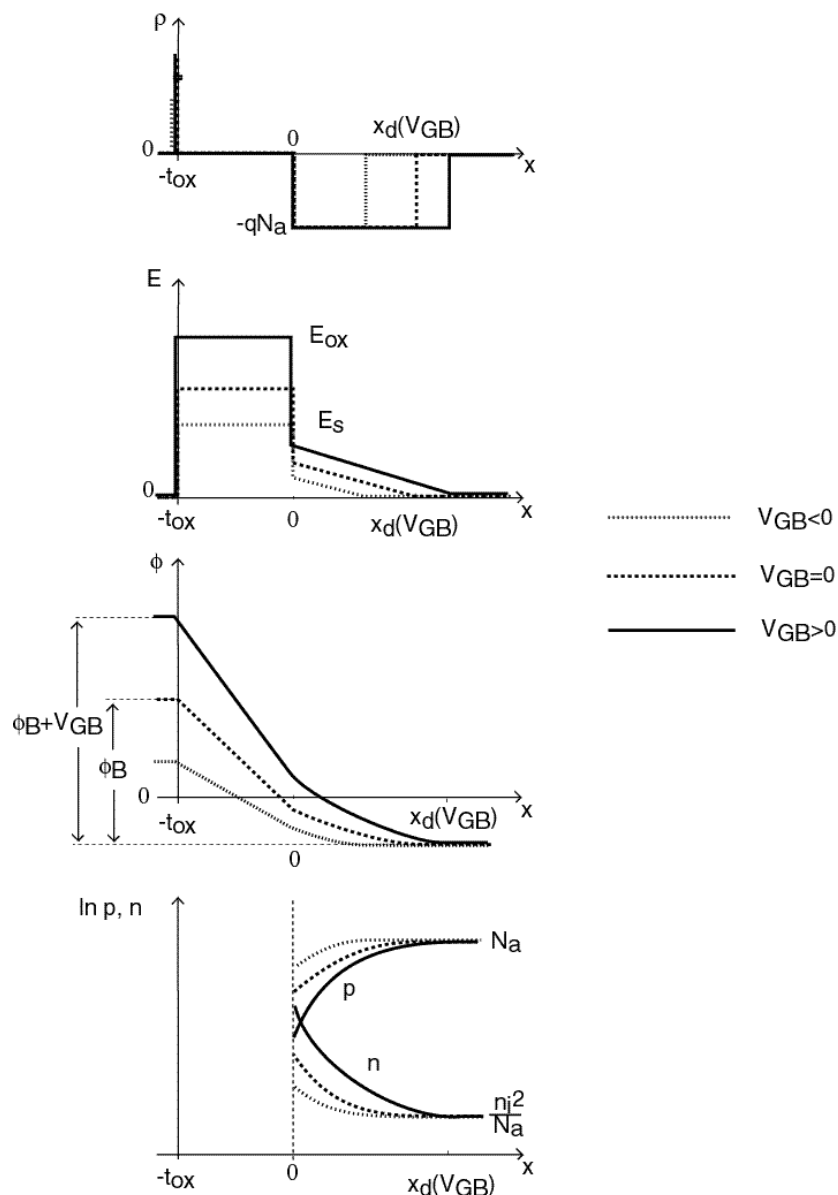
$$\mathbf{np} = \mathbf{n}_i^2 \quad \text{at every } \mathbf{x}$$

[not the case in p-n junction of BJT under bias]

2. Depletion regime

For $V_{GB} > 0$, metal attracts electrons and repels holes
 \Rightarrow *Depletion region widens*

For $V_{GB} < 0$, metal repels electrons and attracts holes
 \Rightarrow *Depletion region shrinks*



In depletion regime, all results obtained for thermal equilibrium apply if $\phi_B \rightarrow \phi_B + V_{GB}$.

For example:

Depletion region thickness:

$$x_d(V_{GB}) = \frac{\epsilon_s}{C_{ox}} \left[\sqrt{1 + \frac{2C_{ox}^2 (\phi_B + V_{GB})}{\epsilon_s q N_a}} - 1 \right]$$

Potential drop across semiconductor SCR:

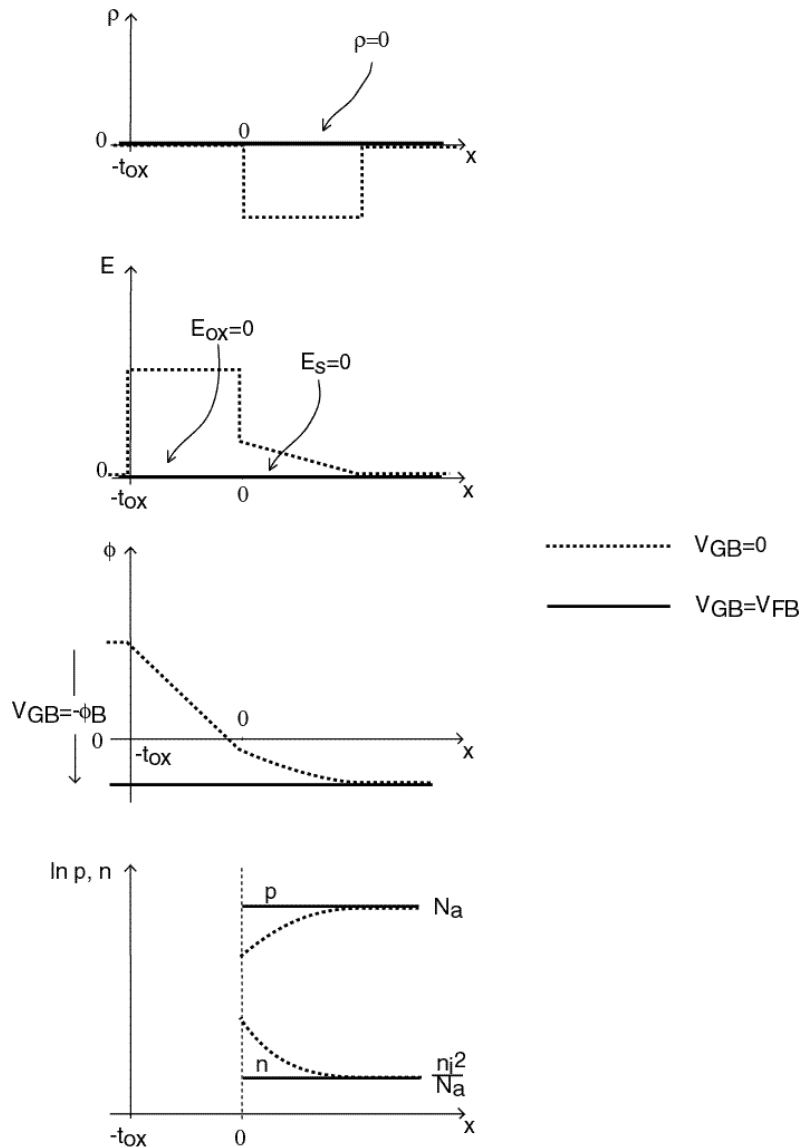
$$V_B(V_{GB}) = \frac{q N_a x_d^2(V_{GB})}{2\epsilon_s}$$

Potential drop across oxide:

$$V_{ox}(V_{GB}) = \frac{q N_a x_d(V_{GB}) t_{ox}}{\epsilon_{ox}}$$

3. Flatband

At a certain negative V_{GB} , depletion region is wiped out \Rightarrow *Flatband*

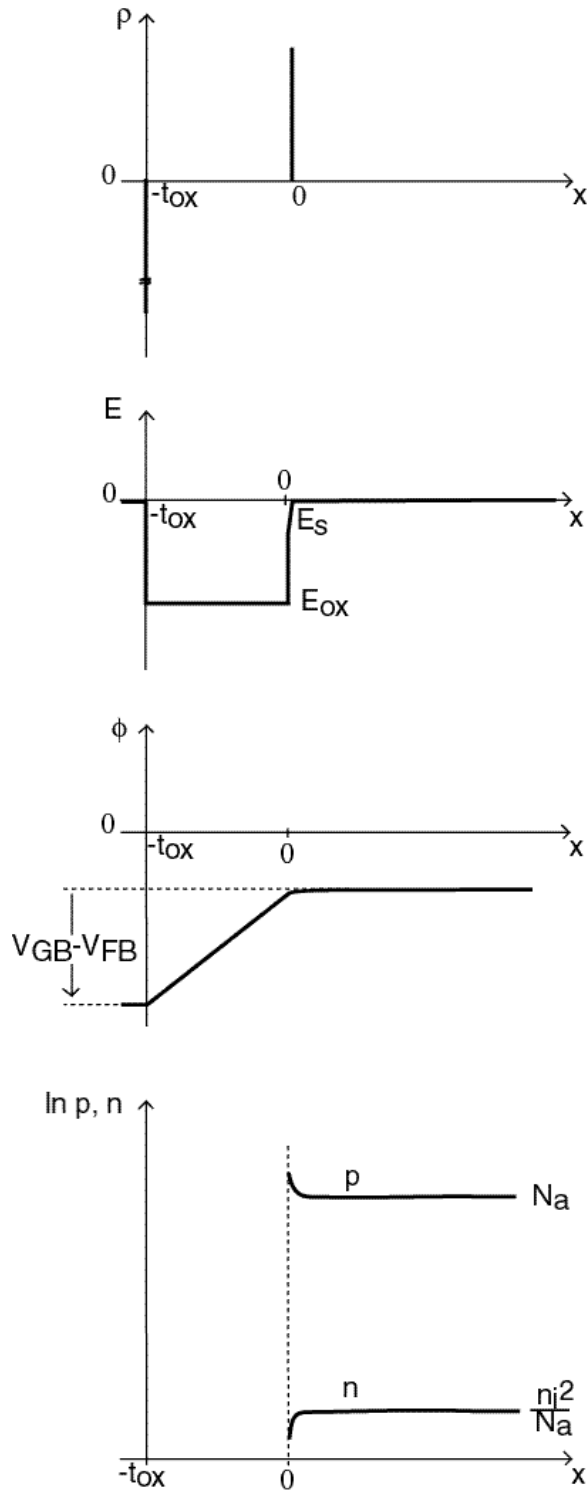


Flatband Voltage:

$$V_{FB} = -\phi_B$$

4. Accumulation regime

If $V_{GB} < V_{FB}$ accumulation of holes at Si/SiO₂ interface

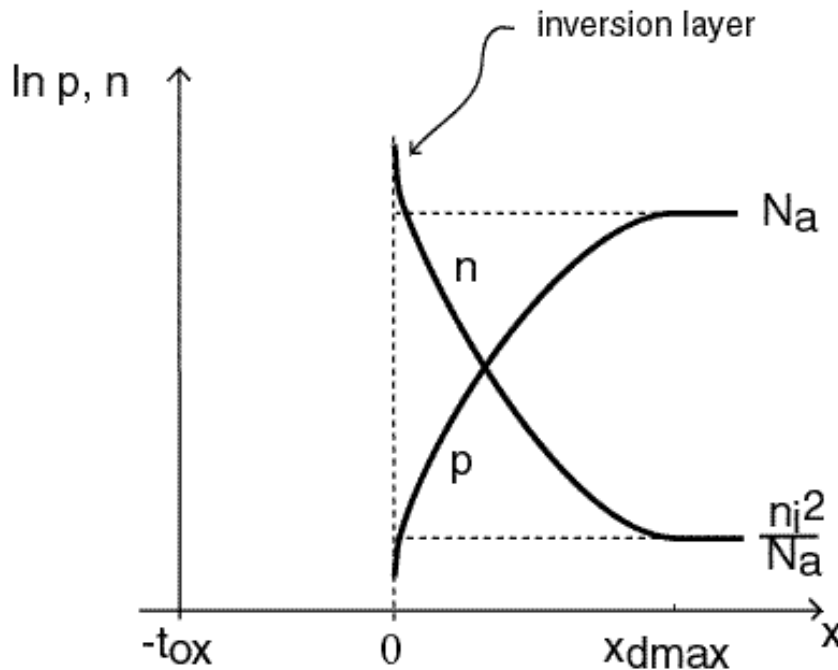


5. Theshold

Back to $V_{GB} > 0$.

For sufficiently large $V_{GB} > 0$, electrostatics change when $n(0) = N_a \Rightarrow$ *threshold*.

Beyond *threshold*, we **cannot** neglect contributions of electrons towards electrostatics.



Let's compute the gate voltage (*threshold voltage*) that leads to $n(0) = N_a$.

Key assumption: use electrostatics of depletion (neglect electron concentration at threshold)

Computation of threshold voltage.

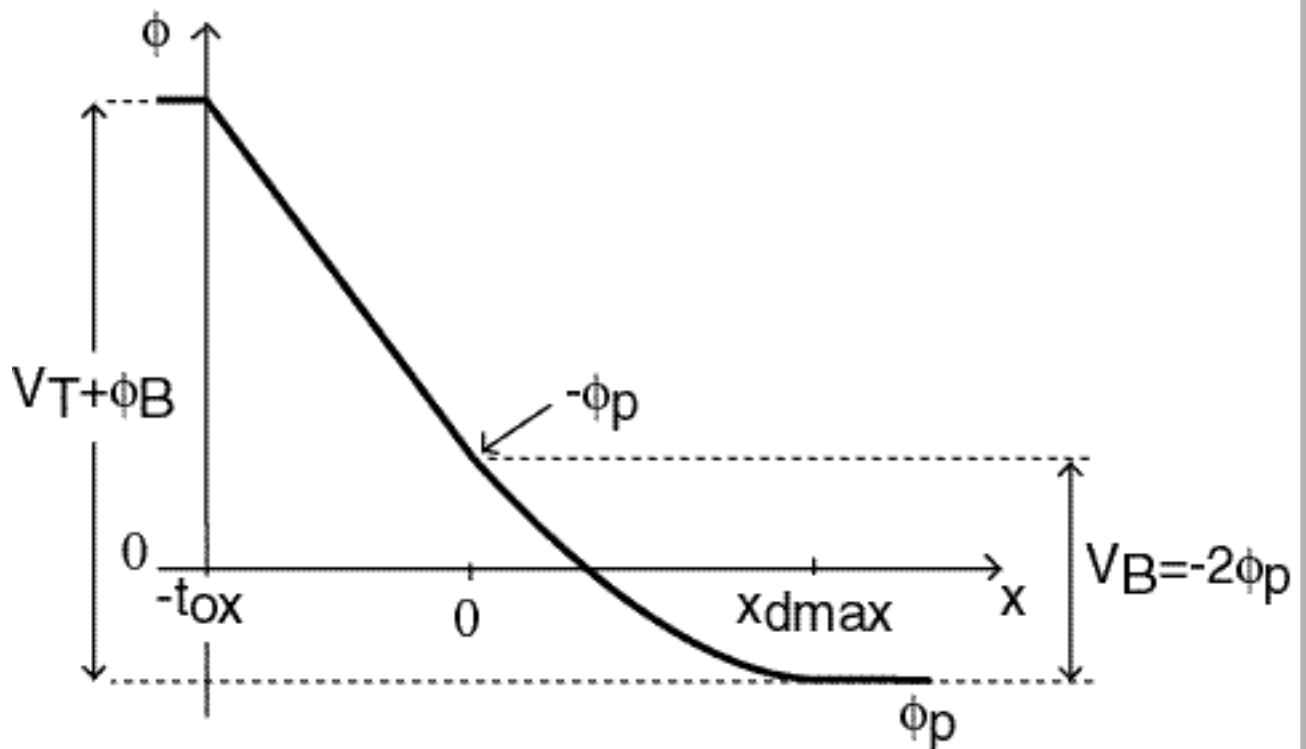
Three step process:

First, compute potential drop in semiconductor at threshold. Start from:

$$n(0) = n_i e^{q\phi(0)/kT}$$

Solve for $\phi(0)$ at $V_{GB} = V_T$:

$$\phi(0) \Big|_{V_{GB}=V_T} = \frac{kT}{q} \cdot \ln \frac{n(0)}{n_i} \Big|_{V_{GB}=V_T} = \frac{kT}{q} \cdot \ln \frac{N_a}{n_i} = -\phi_p$$



Hence:

$$V_B(V_T) = -2\phi_p$$

Computation of threshold voltage.(contd.)

Second, compute potential drop in oxide at threshold.

Obtain $x_d(V_T)$ using relationship between V_B and x_d in depletion:

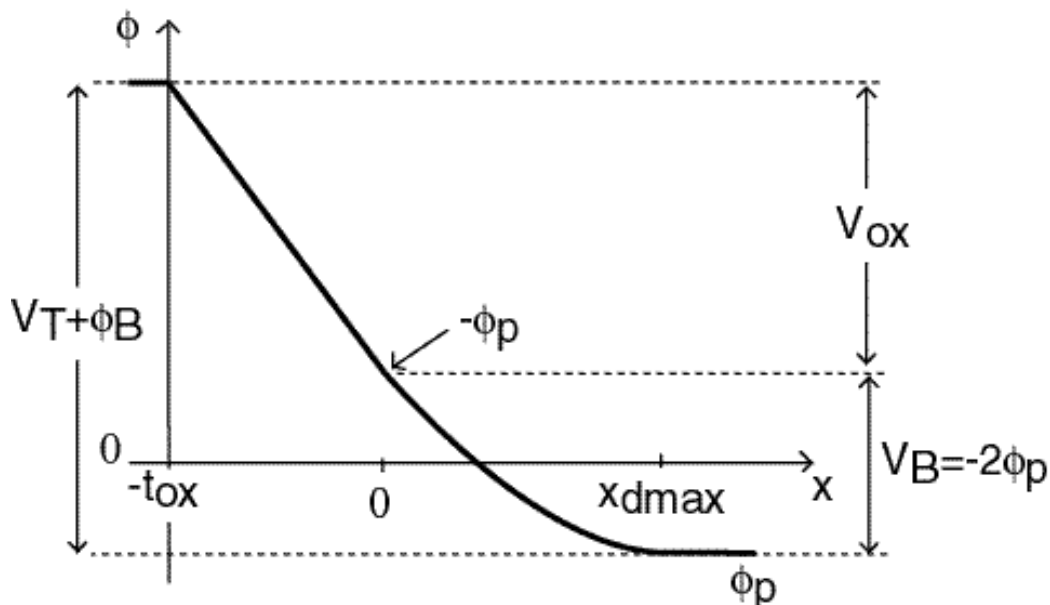
$$V_B(V_{GB} = V_T) = \frac{qN_a x_d^2(V_T)}{2\epsilon_s} = -2\phi_p$$

Solve for x_d at $V_{GB} = V_T$:

$$x_d(V_T) = x_{dmax} = \sqrt{\frac{2\epsilon_s(-2\phi_p)}{qN_a}}$$

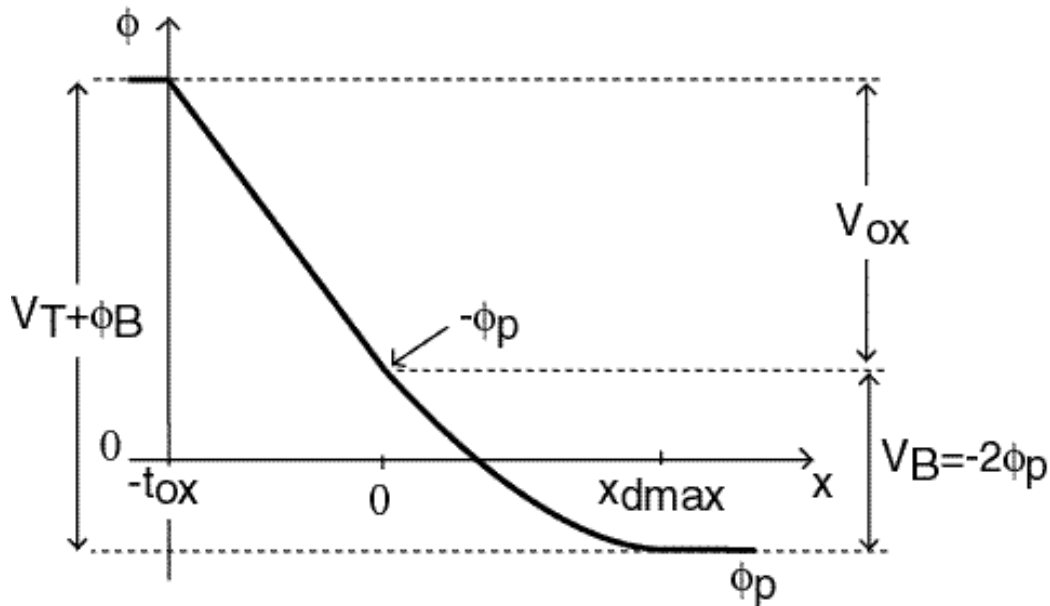
Then:

$$V_{ox}(V_T) = E_{ox}(V_T)t_{ox} = \frac{qN_a x_d(V_T)}{\epsilon_{ox}} t_{ox} = \frac{1}{C_{ox}} \sqrt{2\epsilon_s qN_a (-2\phi_p)}$$



Computation of threshold voltage. (contd.)

Finally, sum potential drops across structure.



$$V_T + \phi_B = V_B(V_T) + V_{ox}(V_T) = -2\phi_P + \frac{1}{C_{ox}} \sqrt{2\epsilon_s q N_a (-2\phi_p)}$$

Solve for V_T :

$$V_T = V_{FB} - 2\phi_P + \frac{1}{C_{ox}} \sqrt{2\epsilon_s q N_a (-2\phi_p)}$$

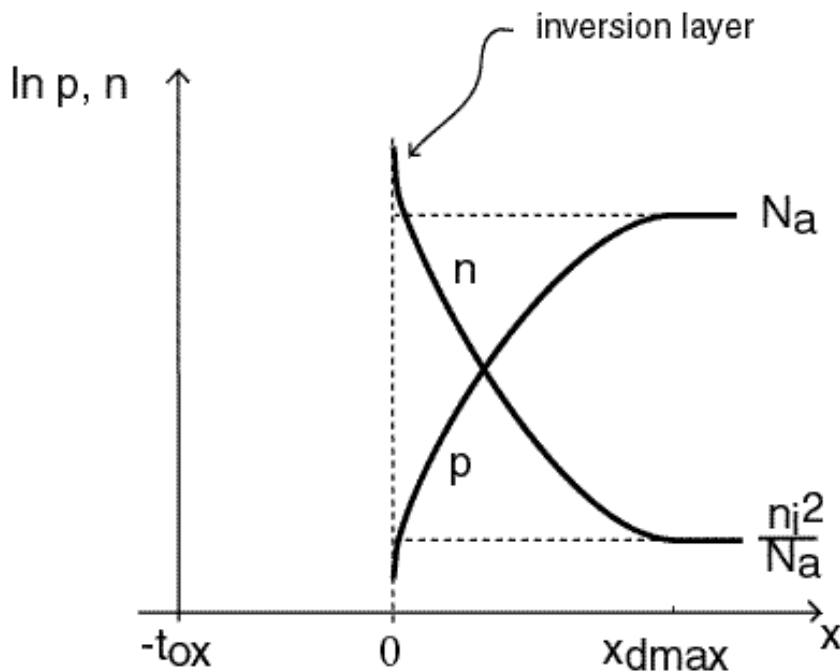
Key dependencies:

- If $N_a \uparrow \rightarrow V_T \uparrow$. The higher the doping, the more voltage required to produce $n(0) = N_a$
- If $C_{ox} \uparrow$ ($t_{ox} \downarrow$) $\rightarrow V_T \downarrow$. The thinner the oxide, the less voltage dropped across the oxide.

6. Inversion

What happens for $V_{GB} > V_T$?

More electrons at Si/SiO₂ interface than acceptors
⇒ *inversion*.



Electron concentration at Si/SiO₂ interface modulated by $V_{GB} \Rightarrow V_{GB} \uparrow \rightarrow n(0) \uparrow |Q_n| \uparrow$:

Field-effect control of mobile charge density!

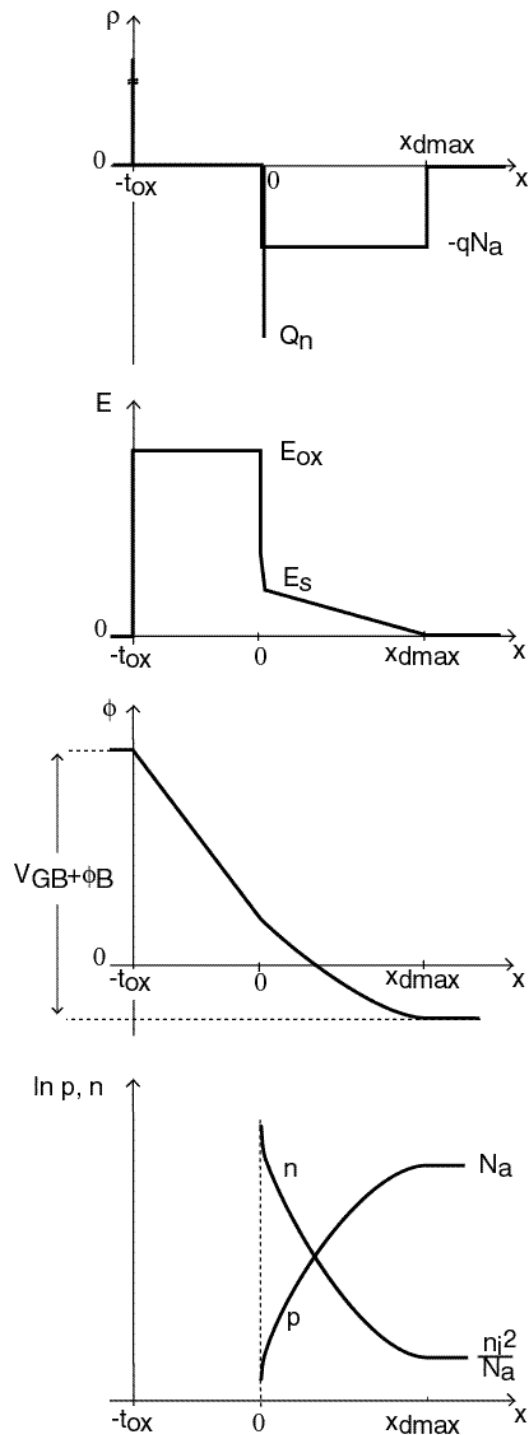
[essence of MOSFET]

Want to compute Q_n vs. V_{GB} [*charge-control relation*]

Make *sheet charge approximation*: electron layer at Si/SiO₂ is much thinner than any other dimension in problem (t_{ox} , x_d).

Charge-Control Relation

To derive the charge-control relation, let's look at the overall electrostatics:



Charge-Control Relation (contd.)

Key realization:

$$|Q_n| \propto n(0) \propto e^{q\phi(0)/kT}$$

$$|Q_d| \propto \sqrt{\phi(0)}$$

Hence, as $V_{GB} \uparrow$ and $\phi(0) \uparrow$, $|Q_n|$ will change a lot, but $|Q_d|$ will change very little.

Several consequences:

- x_d does not increase much beyond threshold:

$$x_d(\text{inv.}) \approx x_d(V_T) = \sqrt{\frac{2\epsilon_s(-2\phi_p)}{qN_a}} = x_{d,\max}$$

- V_B does not increase much beyond $V_B(V_T) = -2\phi_p$ (a thin sheet of electrons does not contribute much to V_B):

$$V_B(\text{inv.}) \approx V_B(V_T) = -2\phi_p$$

Charge-Control Relation (contd.)

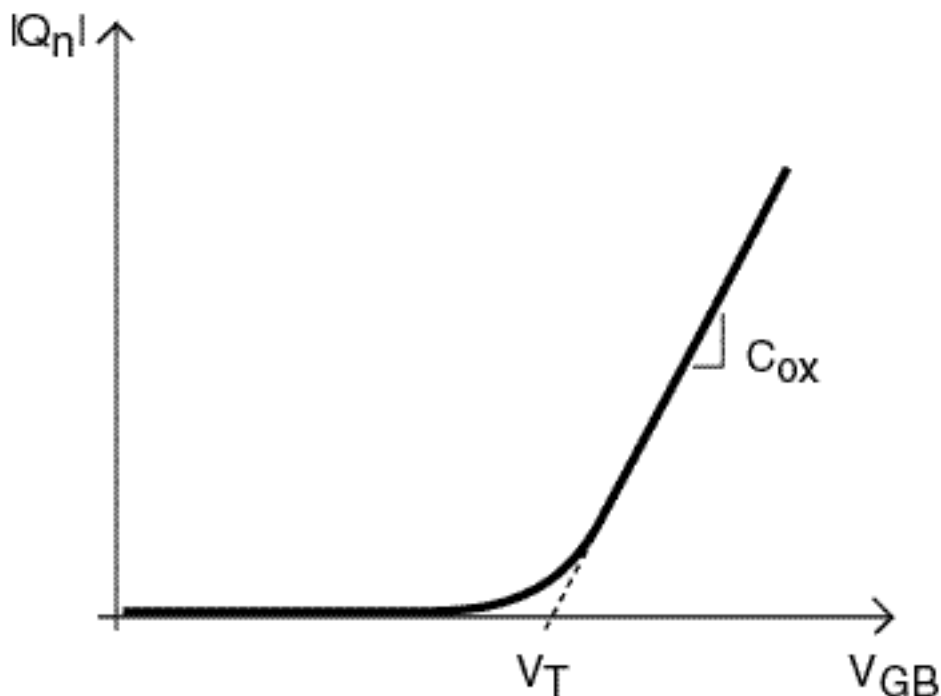
- All extra voltage beyond V_T used to increase inversion charge Q_n . Think of it as capacitor:
 - Top plate: metal gate
 - Bottom plate: inversion layer

$$Q = CV$$

\Rightarrow

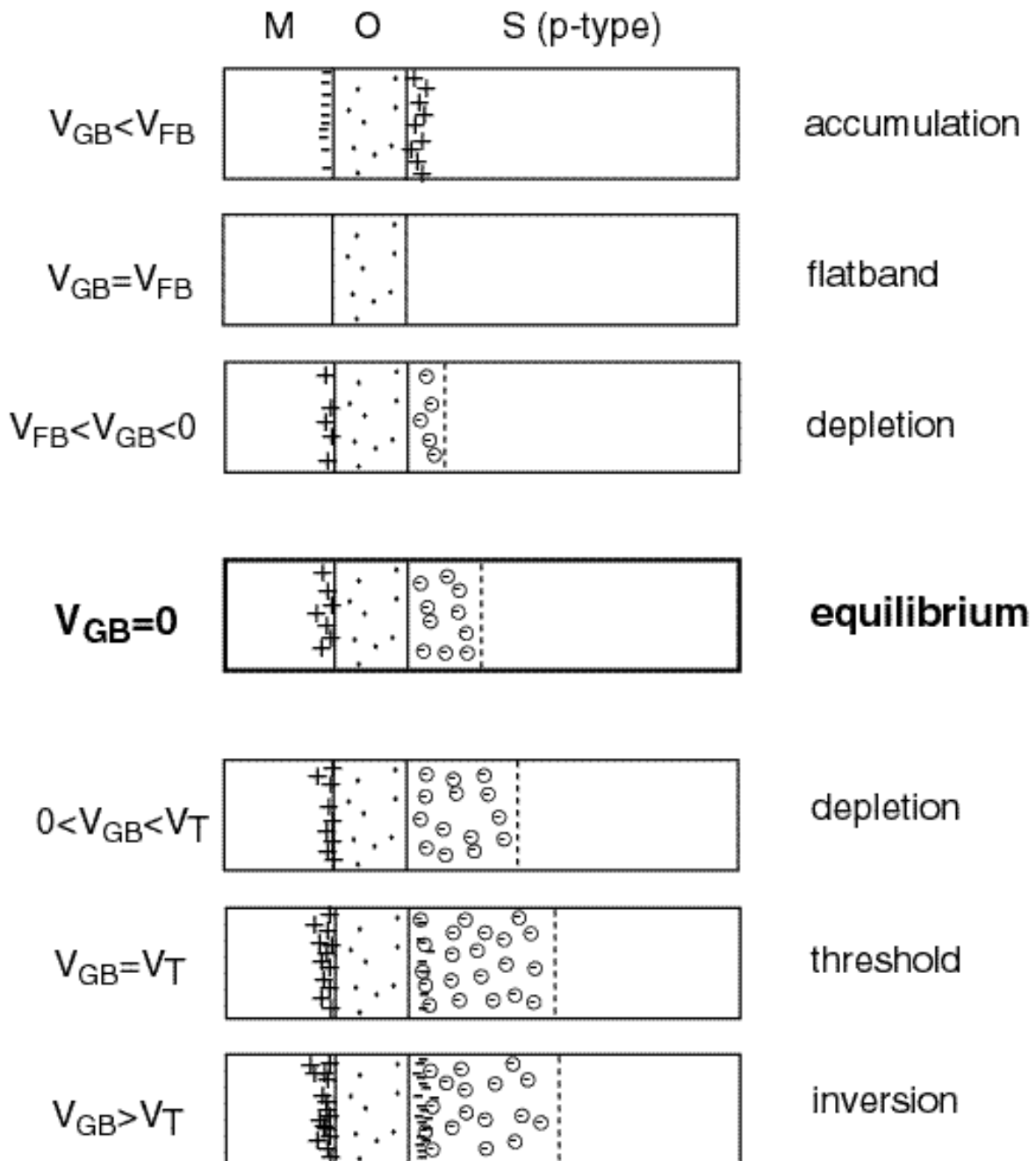
$$Q_n = -C_{ox}(V_{GB} - V_T) \quad \text{for } V_{GB} > V_T$$

Existence of Q_n and control over Q_n by V_{GB}
 \Rightarrow key to MOS electronics



What did we learn today?

Summary of Key Concepts



In inversion:

$$|Q_n| = C_{ox} (V_{GB} - V_T) \quad \text{for } V_{GB} > V_T$$